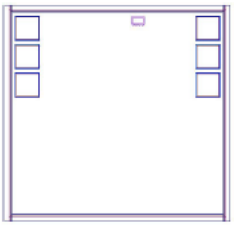
MMIC

REFLECTIONLESS FILTER DICE

50Ω DC to 21 GHz



X-Series

Available in Low Pass, High Pass and Band Pass designs

The Big Deal

- *Patented design eliminates in band spurs*
- *Pass band cut-off up to 21 GHz*
- *Stop band up to 35 GHz*
- *Excellent repeatability through IPD* process*
- *Unpackaged Die Form*

Product Overview

Mini-Circuits' X-Series reflectionless filters employ a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level which interact with neighboring components and often result in intermodulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolators, isolation amplifiers or attenuators.

Key Features	Advantages
Easy integration with sensitive reflective components, e.g. mixers, multipliers	Reflectionless filters absorb unwanted signals, preventing reflections back to the source. This reduces generation of additional unwanted signals without the need for extra components like attenuators, improving system dynamic range and saving board space.
Enables stable integration of wideband amplifiers	Because reflectionless filters maintain good impedance in the stop band; they can be integrated with high gain, wideband amplifiers without the risk of creating instabilities in these out of band regions.
Cascadable	Reflectionless filters can be cascaded in multiple sections to provide sharper and higher attenuation, while also preventing any standing waves that could affect pass band signals.
Excellent power handling in a tiny surface mount device	High power handling extends the usability of these filters to the transmit path for inter-stage filtering.
Excellent repeatability of RF performance	Through semiconductor IPD process, X-series filters are inherently repeatable for large volume production.
Excellent stability over temperature	With ±0.3 dB variation over temperature ideal for use in wide temperature range applications without the need for additional temperature compensation.
Operating Temperature up to 105°C	Suitable for operation close to high power components
Unpackaged Die form	Enables direct integration into customer hybrids

*IPD – Integrated Passive Device, is a GaAs semiconductor process

Reflectionless

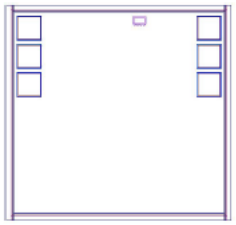
High Pass Filter Die

XHF-1162-D+

50Ω 11.6 to 40 GHz

Features

- Match to 50Ω in the stop band, eliminates undesired reflections
- Cascadable
- Excellent Power handling
- Protected by US Patent No. 8,392,495



+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Ordering Information: Refer to Last Page

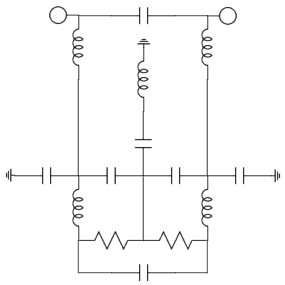
Applications

- Wi-Fi
- WiMax
- Microwave Radio
- Military & Space

General Description

Mini-Circuits' XHF-1162-D+ reflectionless filter die employs a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level. These reflections interact with neighboring components and often result in inter-modulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

Simplified Schematic



Pad	Description
RF-IN	RF Input Pad
RF-OUT	RF Output Pad
Ground	Ground Bonding Pad

Note: 1. Bond Pad material - Gold
2. Bottom of Die - Gold plated

Electrical Specifications[1] at 25°C

Parameter		F#	Frequency (MHz)	Min.	Typ.	Max.	Unit
Stop Band	Rejection	DC - F[1]	DC - 2500	—	11.0	—	dB
		F[1] - F1	2500 - 9100	—	21.3	—	
	Frequency Cut-off	F2	10500	—	3.0	—	dB
	VSWR	DC - F[1]	DC - 2500	—	2.3	—	:1
		F[1] - F1	2500 - 9100	—	1.4	—	
Pass Band	Insertion Loss	F3 - F4	11600 - 30000	—	1.3	—	dB
		F4 - F5	30000 - 40000	—	1.8	—	
	VSWR	F3 - F4	11600 - 30000	—	1.3	—	:1
		F4 - F5	30000 - 40000	—	1.8	—	:1

[1] Electrical Specifications are typical measured characteristics of die.

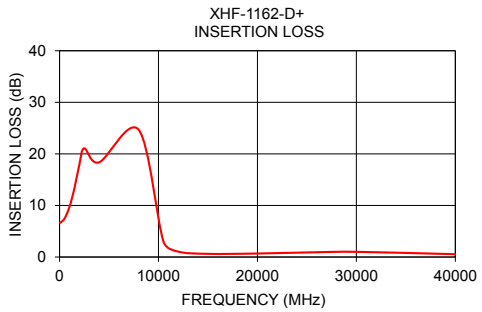
Absolute Maximum Ratings[4]

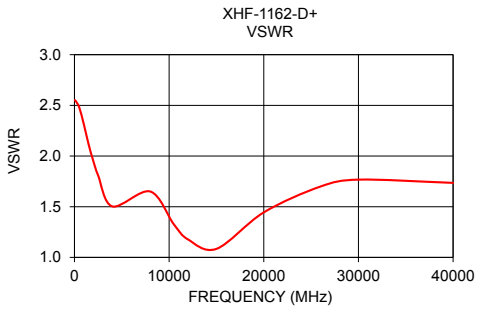
Parameter	Ratings
Operating Temperature	-55°C to +105°C
RF Power Input, Passband (F3-F5)[2]	1.26W at 25°C
RF Power Input, Stopband (DC-F3)[3]	0.25W at 25°C

[2] Passband rating derates linearly to 0.63W at 105°C ambient
[3] Stopband rating derates linearly to 0.12W at 105°C ambient
[4] Permanent damage may occur if any of these limits are exceeded.

Typical Performance Data at 25°C

Frequency (MHz)	Insertion Loss (dB)	VSWR (:1)
10	6.66	2.55
50	6.67	2.55
100	6.69	2.55
500	7.45	2.48
1000	9.71	2.31
1500	13.31	2.11
2000	17.91	1.95
2500	21.08	1.81
4000	18.37	1.50
8000	24.67	1.65
10500	3.02	1.33
12000	1.06	1.18
15000	0.62	1.08
20000	0.68	1.44
26000	0.93	1.70
30000	1.01	1.77
40000	0.55	1.74





Characterization Test Circuit

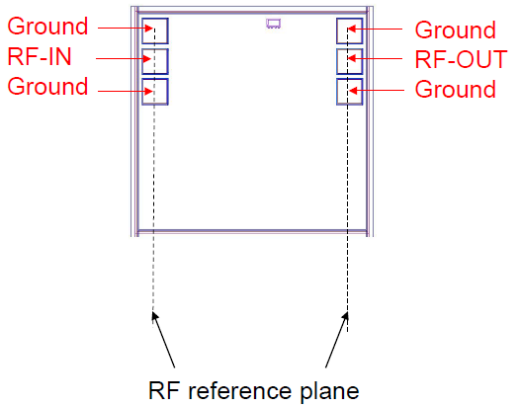


Figure 1: Block Diagram of Test Circuit used for characterization of S-parameters

Conditions:
1. Input Power= -25dBm

Die Layout

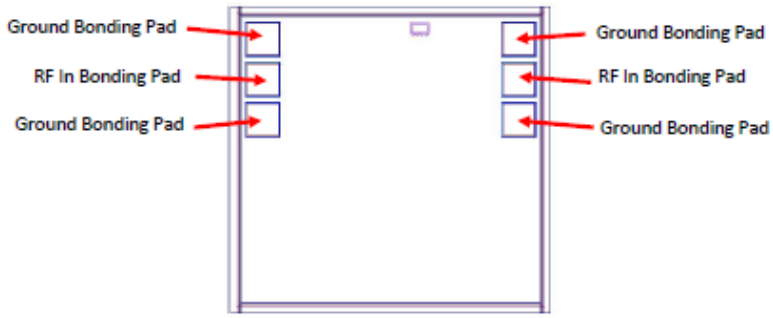


Fig 2. Die Layout

Bonding Pad Position

(Dimensions in µm, Typical)

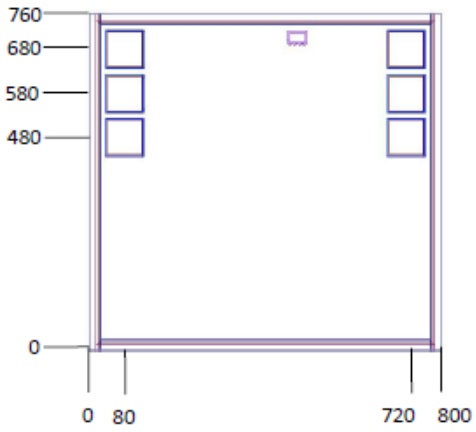


Fig 3. Bonding Pad Positions

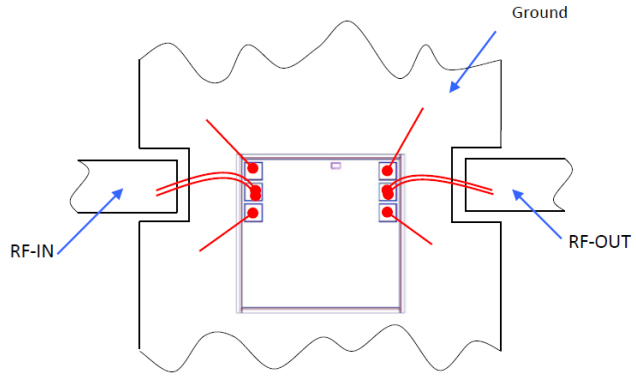
Critical Dimensions

Parameter	Values
Die Thickness, µm	100
Die Width, µm	800
Die Length, µm	760
Bond Pad Size (Ground pad), µm	75 x 75

Assembly and Handling Procedure

1. Storage
   Dice should be stored in a dry nitrogen purged desiccators or equivalent.
2. ESD
   MMIC Gallium Arsenide (GaAs) filter dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static worksta tion. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.
3. Die Attach
   The die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are DieMat DM6030Hk-PT/H579/H579 or Ablestik 84-1LMISR4. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufac turer's cure condition. It is recommended to use antistatic die pick up tools only.
4. Wire Bonding
   Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.

Assembly Diagram

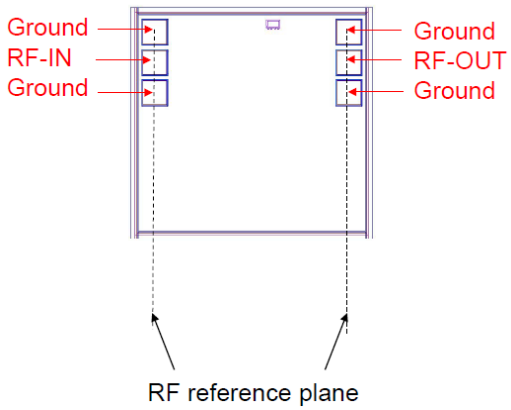


Note: Ground bond wires are optional.

Recommended Wire Length, Typical

Wire	Wire Length (mm)	Wire Loop Height (mm)
All wires	1.0	0.15

RF Reference Plane



Additional Detailed Technical Information

additional information is available on our dash board.

Performance Data	Data Table	
	Swept Graphs	
	S-Parameter (S2P Files) Data Set with and without port extension(.zip file)	
Case Style	Die	
Die Ordering and packaging information	Quantity, Package	Model No.
	Small, Gel - Pak: 10,50,100 KGD*	XHF-1162-DG+
	Medium†, Partial wafer: KGD*<1980	XHF-1162-DP+
	Large†, Full wafer	XHF-1162-DF+
	†*Available upon request contact sales representative*	
	Refer to AN-60-067	
Environmental Ratings	ENV-80	

*Known Good Dice ("KGD") means that the dice are taken from PCM good wafer and visually inspected according to Mini-Circuits inspection criteria. While this is not definitive, it does help to provide a higher degree of confidence that dice are capable of meeting typical RF electrical parameters specified by Mini-Circuits.

ESD Rating**

Human Body Model (HBM): Class 1A (250V) in accordance with ANSI/ESD STM 5.1 - 2001

** Tested in industry standard MCLP 3x3mm 12 lead package.

Additional Notes

A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.

B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.

C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the Standard Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/MCLStore/terms.jsp

D. Mini-Circuits does not warrant the accuracy or completeness of the information, text, graphics and other items contained within this document and same are provided as an accommodation and on an "As is" basis, with all faults.

E. Purchasers of this part are solely responsible for proper storing, handling, assembly and processing of Known Good Dice (including, without limitation, proper ESD preventative measures, die preparation, die attach, wire bond ing and related assembly and test activities), and Mini-Circuits assumes no responsibility therefor or for environmental effects on Known Good Dice.

F. Mini-Circuits and the Mini-Circuits logo are registered trademarks of Scientific Components Corporation d/b/a Mini-Circuits. All other third-party trademarks are the property of their respective owners. A reference to any third-party trademark does not constitute or imply any endorsement, affiliation, sponsorship, or recommendation by any such third-party of Mini-Circuits or its products.